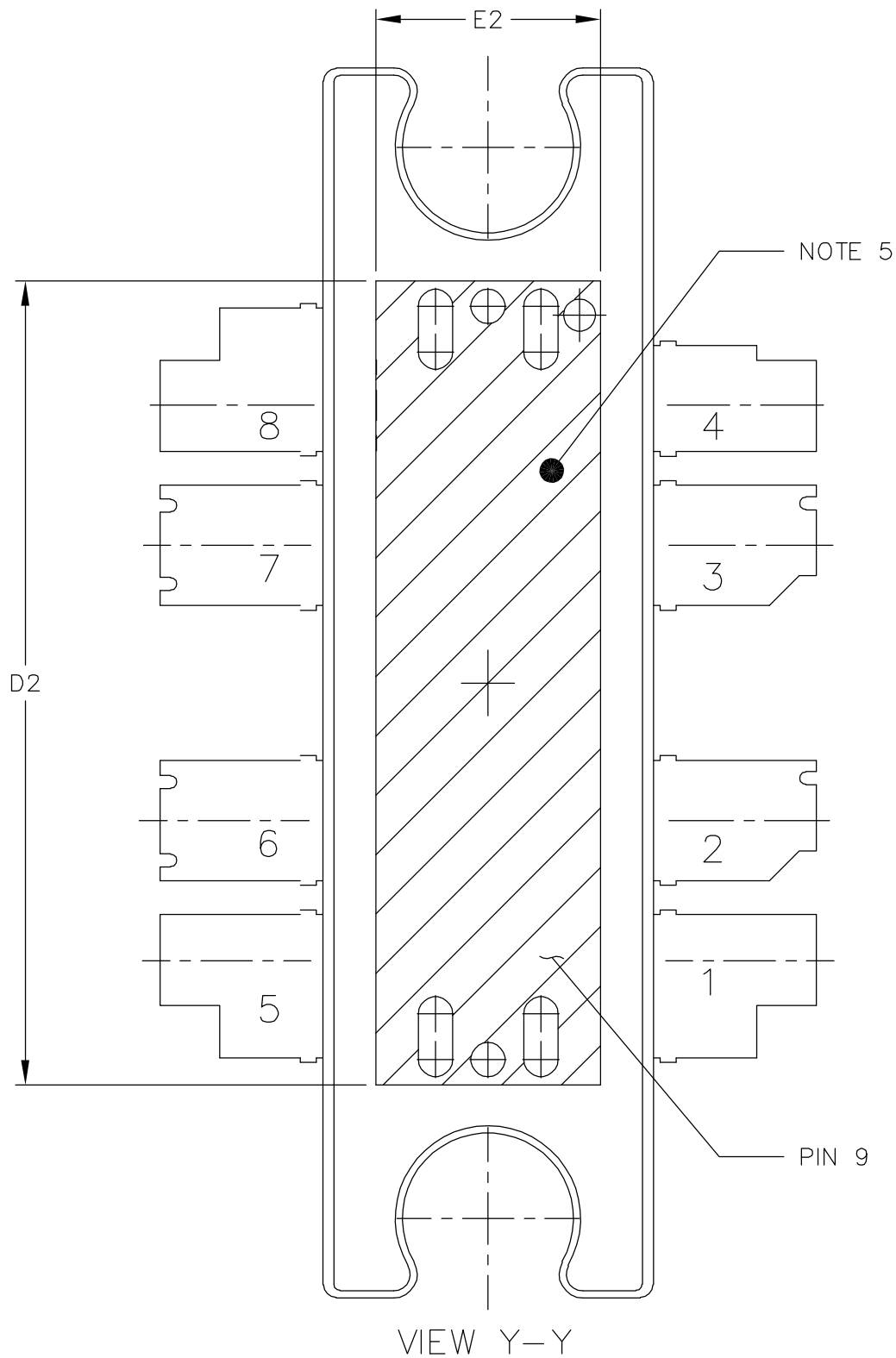


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: TO-272, 8 LEAD PLASTIC	DOCUMENT NO: 98ASA10537D	REV: E
	STANDARD: NON-JEDEC	
	SOT1742-1	19 JAN 2016



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: TO-272, 8 LEAD PLASTIC	DOCUMENT NO: 98ASA10537D REV: E	
	STANDARD: NON-JEDEC	
	SOT1742-1	19 JAN 2016



NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
4. DIMENSIONS "b" AND "b1" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" AND "b2" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
5. CROSSHATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.
6. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.

STYLE 1:

PIN 1 - SOURCE (COMMON)	PIN 5 - SOURCE (COMMON)
PIN 2 - DRAIN	PIN 6 - GATE
PIN 3 - DRAIN	PIN 7 - GATE
PIN 4 - SOURCE (COMMON)	PIN 8 - SOURCE (COMMON)
	PIN 9 - SOURCE (COMMON)

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.098	.106	2.49	2.69	b	.105	.111	2.67	2.82
A1	.038	.044	0.96	1.12	b1	.088	.094	2.24	2.39
A2	.040	.042	1.02	1.07	b2	.066	.072	1.68	1.83
D	.926	.934	23.52	23.72	b3	.067	.073	1.70	1.85
D1	.810 BSC		20.57 BSC		b4	.077	.083	1.96	2.11
D2	.604	----	15.34	----	c1	.007	.011	.178	.279
E	.492	.500	12.50	12.70	e	.104 BSC		2.64 BSC	
E1	.246	.254	6.25	6.45	e1	.210 BSC		5.33 BSC	
E2	.162	----	4.11	----	e2	.229 BSC		5.82 BSC	
E3	.241	.245	6.12	6.22					
F	.025 BSC		0.64 BSC		aaa	.004		0.1	
P	.126	.134	3.20	3.40	bbb	.008		0.2	

© NXP SEMICONDUCTORS N.V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:

TO-272, 8 LEAD
PLASTIC

DOCUMENT NO: 98ASA10537D

REV: E

STANDARD: NON-JEDEC

SOT1742-1

19 JAN 2016